

# Lecture 24 - The Si surface and the Metal-Oxide-Semiconductor Structure (*cont.*)

## The "Long" Metal-Oxide-Semiconductor Field-Effect Transistor

April 6, 2007

### Contents:

1. Dynamics of the MOS structure (*cont.*)
2. Three-terminal MOS structure
3. Introduction to MOSFET

### Reading assignment:

del Alamo, Ch. 8, §§8.5-8.6; Ch. 9, §9.1

## Key questions

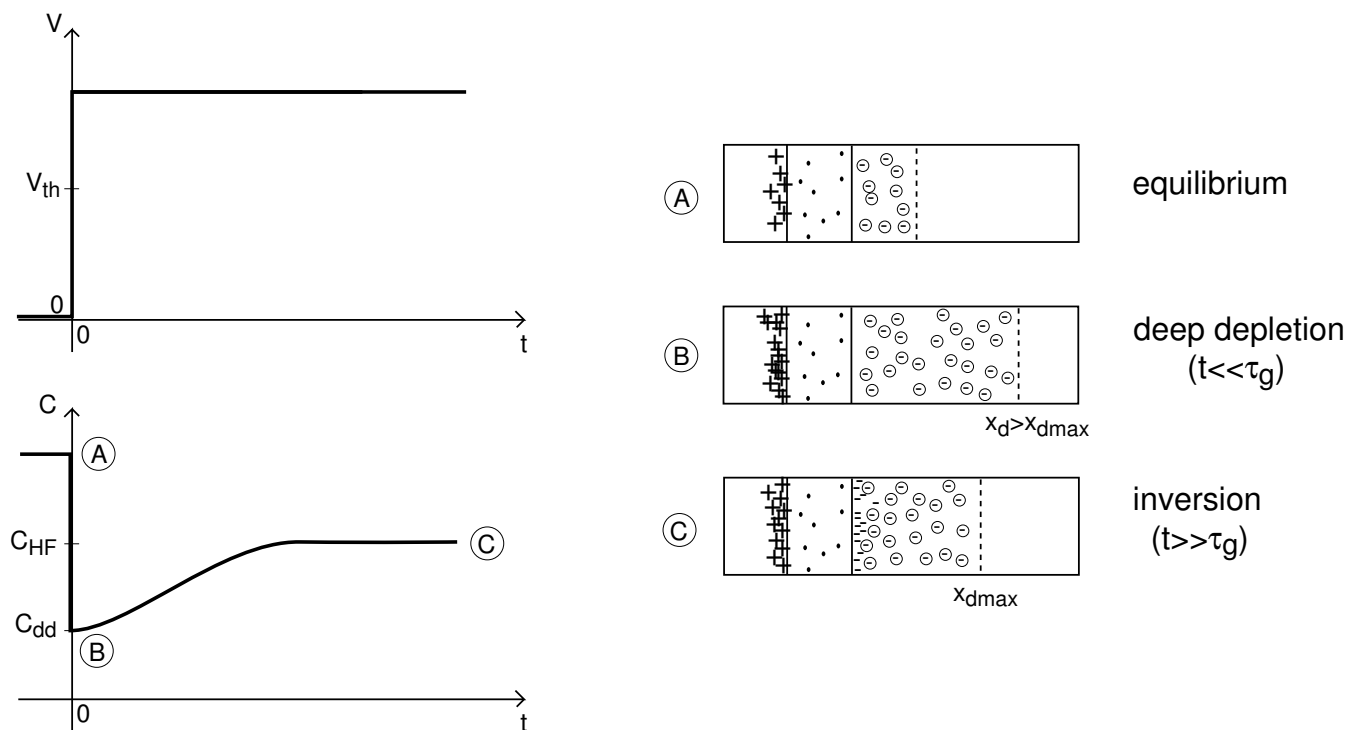
- What happens to the C-V characteristics of a MOS structure if the *bias* is switched abruptly?
- What happens to the electrostatics of the MOS structure if we contact the inversion layer and we apply a bias to it?
- How does a MOSFET look like and how does it work (roughly)?

# 1. Dynamics of the MOS structure (*cont.*)

## □ Deep depletion

Consider what happens after the application of a voltage step from depletion towards inversion.

On top of step, put HF small signal to measure  $C$



Immediately after the onset of the step (after an  $RC$  delay), inversion layer does not have a chance to grow (electrons must be generated)

→ MOS remains in depletion ("deep depletion")

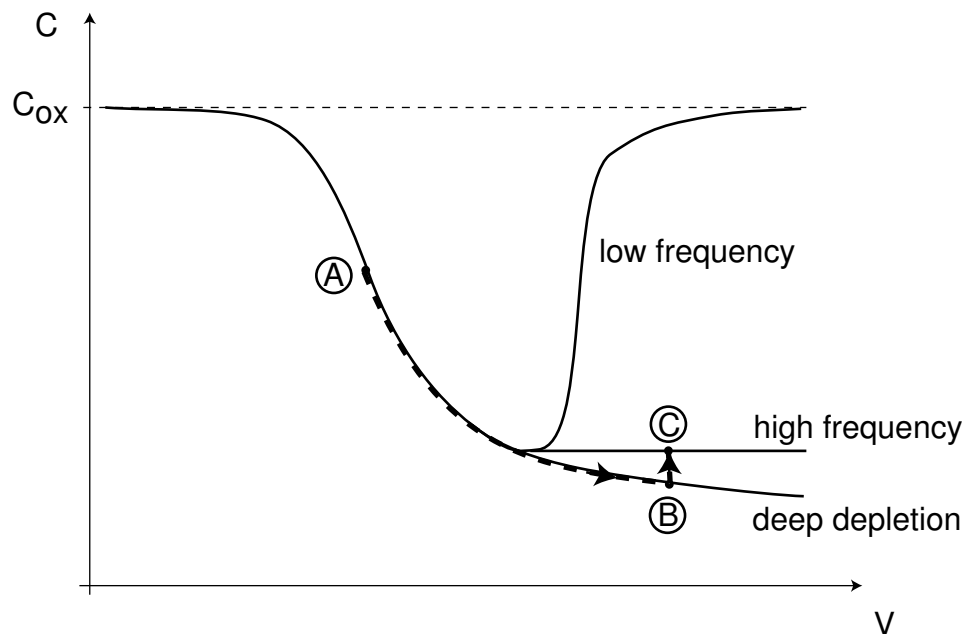
→  $x_d$  grows beyond  $x_{dmax}$

→  $C$  smaller than  $C_{HF}$

Even though  $V > V_{th}$ , capacitance in deep depletion described by expression derived for depletion regime:

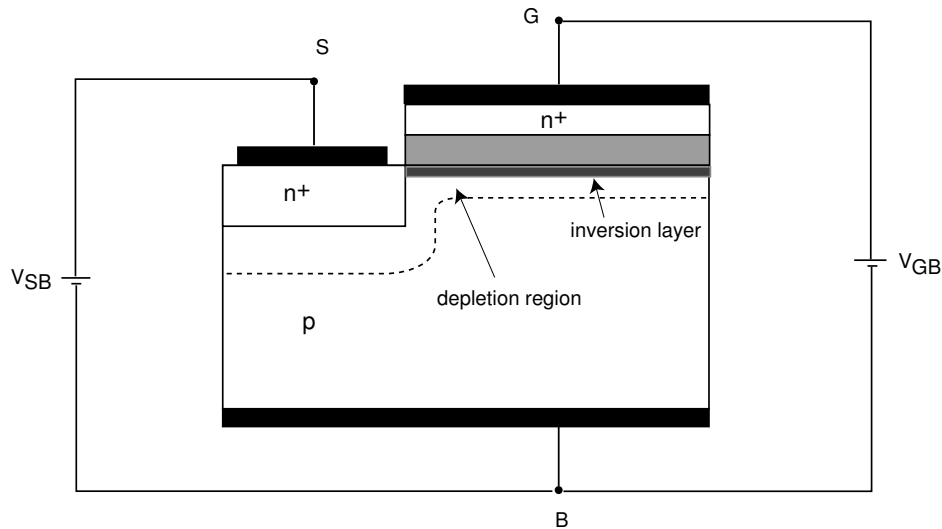
$$C_{dd} \simeq \frac{C_{ox}}{\sqrt{1 + 4\frac{V - V_{FB}}{\gamma^2}}}$$

C-V characteristics:



## 2. Three-terminal MOS structure

Introduce contact to inversion layer:

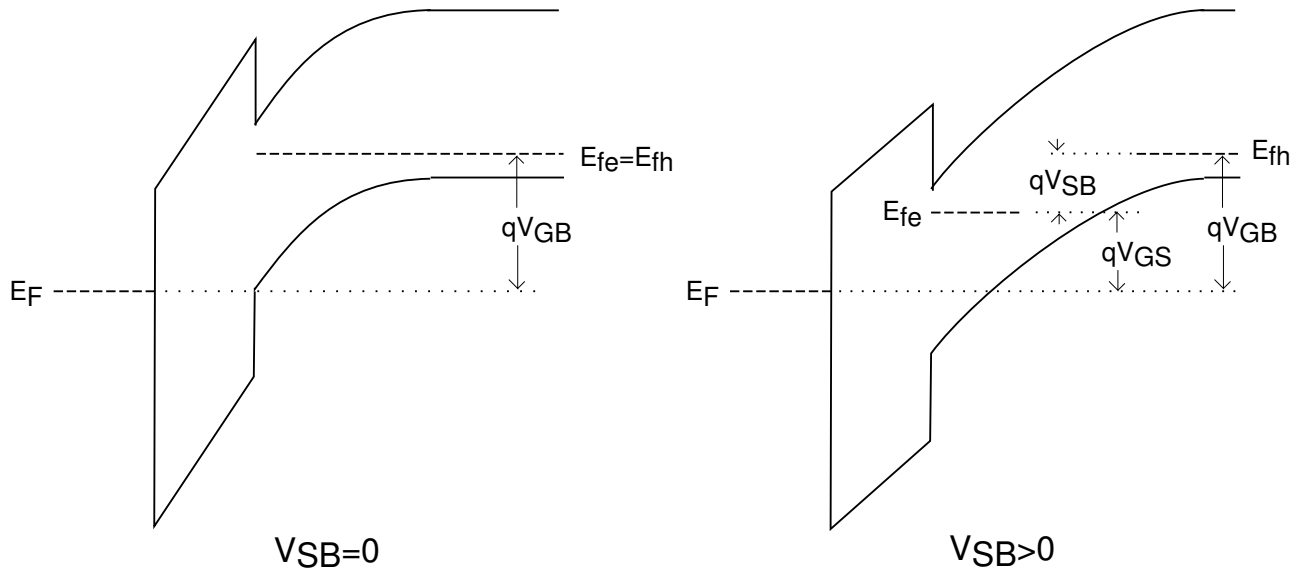


Can now apply bias to inversion layer with respect to substrate,  $V_{SB}$ .

Source-body junction:  $n^+$ -p junction  $\rightarrow$  only reverse bias desired,  $V_{SB} \geq 0$ .

Interested only in inversion regime: apply  $V_{SB} \geq 0$  keeping  $V_{GB}$  constant.

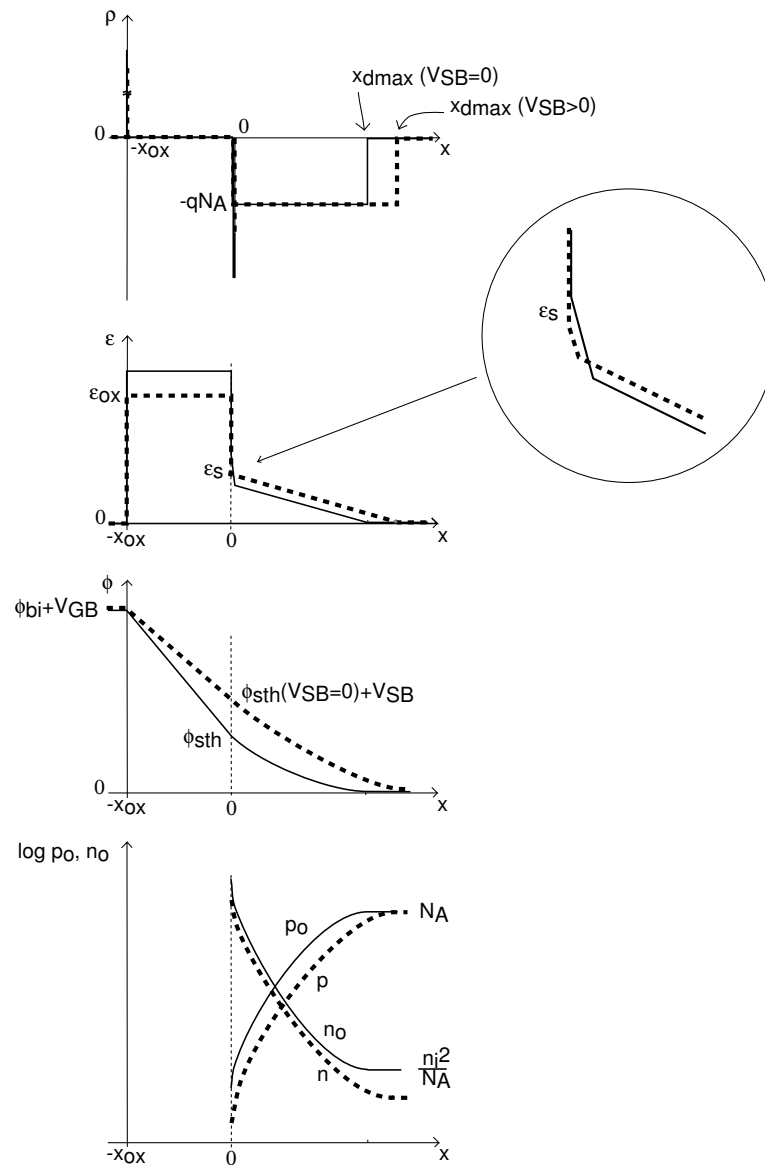
Energy band diagrams:



$$\phi_s(V_{SB}) = \phi_s(V_{SB} = 0) + V_{SB}$$

Application of  $V_{SB} > 0$ , increases  $\phi_s$ , and also  $|Q_d|$ .

$V_{SB} > 0 \Rightarrow x_d \uparrow \quad |Q_d| \uparrow \quad \phi_s \uparrow$  (as in reverse bias p-n junction).



Total potential difference from G to B fixed:

$$\phi_{bi} + V_{GB} = \phi_{ox} + \phi_s$$

Hence:  $\phi_{ox} \downarrow \Rightarrow \mathcal{E}_{ox} \downarrow \quad \mathcal{E}_s \downarrow$

But:

$$\mathcal{E}_s = -\frac{Q_s}{\epsilon_s}$$

Hence:  $|Q_s| \downarrow$

In summary:

$$|Q_s| \downarrow \quad |Q_d| \uparrow \Rightarrow |Q_i| \downarrow$$

equivalent to  $V_{th}$  shifting positive.

Key conclusion: *application of a body bias turns inversion layer off!*

Important implications for device and circuit design and operation.



- $V_{th}$  model that accounts for body bias

Go to Poisson-Boltzmann formulation and change:

$$\phi_{sth} \rightarrow \phi_{sth} + V_{SB}$$

Then:

$$V_{th} = V_{FB} + \phi_{sth} + V_{SB} + \gamma\sqrt{\phi_{sth} + V_{SB}}$$

For MOSFET operation, interested in threshold in  $V_{GS}$ :

$$V_{GB} = V_{GS} + V_{SB}$$

Then:

$$V_{th}^{GS}(V_{SB}) = V_{th}^{GB} - V_{SB} = V_{FB} + \phi_{sth} + \gamma\sqrt{\phi_{sth} + V_{SB}}$$

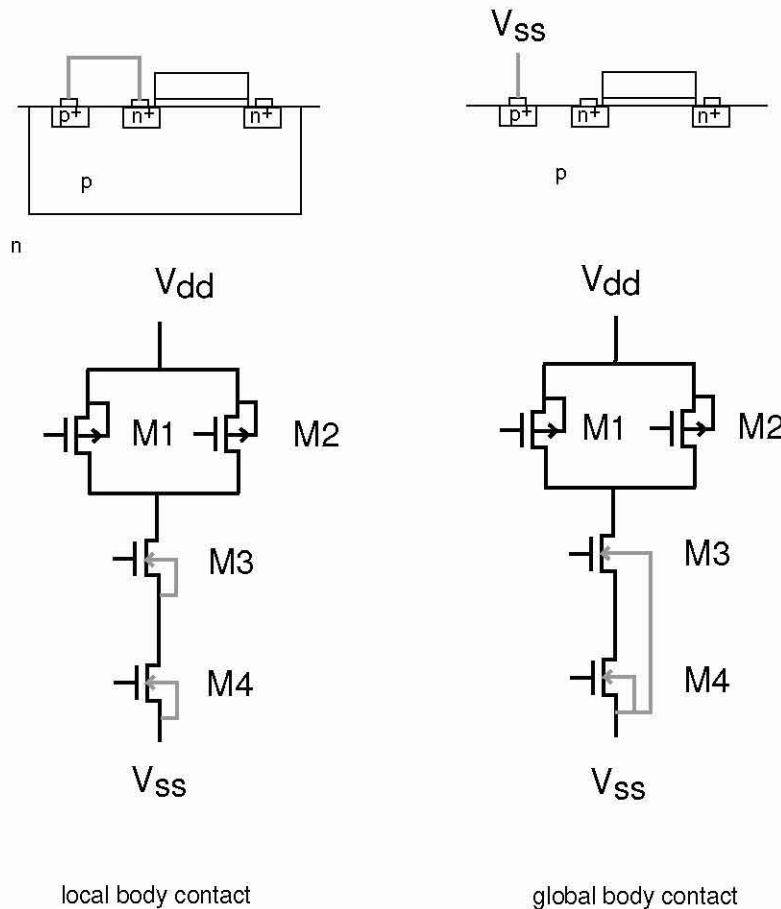
Can easily rewrite as:

$$V_{th}^{GS}(V_{SB}) = V_{th}^{GS}(V_{SB} = 0) + \gamma(\sqrt{\phi_{sth} + V_{SB}} - \sqrt{\phi_{sth}})$$

Note:  $V_{SB} \uparrow \Rightarrow V_{th}^{GS} \uparrow$

## Back bias effect important in MOSFETs and CMOS.

Ideally, the body of every MOSFET should be tied to its source, but that's expensive. What are the trade-offs?



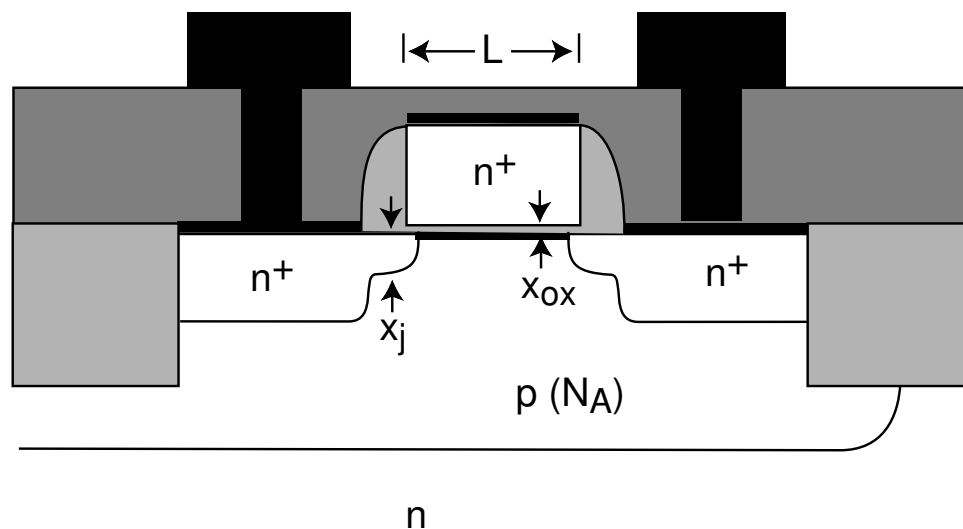
Focus on M3 (nMOSFET) of NAND gate:

- with local body contact:  $V_{SB} = 0$  always  $\Rightarrow V_{th}$  predictable
- with global body contact: sometimes  $V_{SB} > 0 \Rightarrow$  slower switching, "jitter"



Inversion layer current depends on:

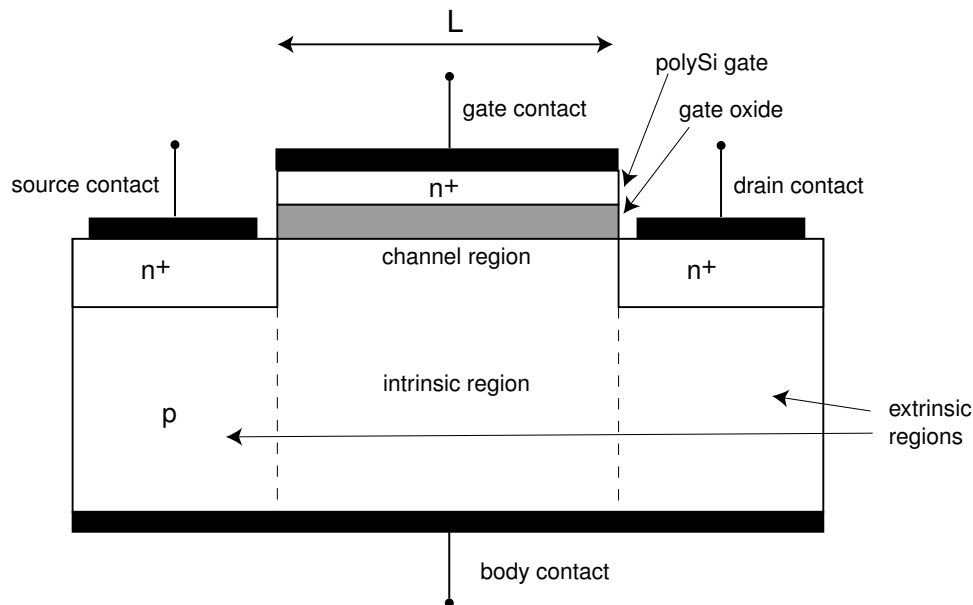
- lateral field across inversion layer (set to first order by drain-to-source voltage)
- electron concentration in inversion layer (set to first order by gate-to-source voltage)



Key design parameters:

- gate length,  $L \simeq$  electrical channel length
- gate oxide thickness,  $x_{ox}$
- source and drain junction depth,  $x_j$
- doping level in body,  $N_A$

## 4. The ideal MOSFET

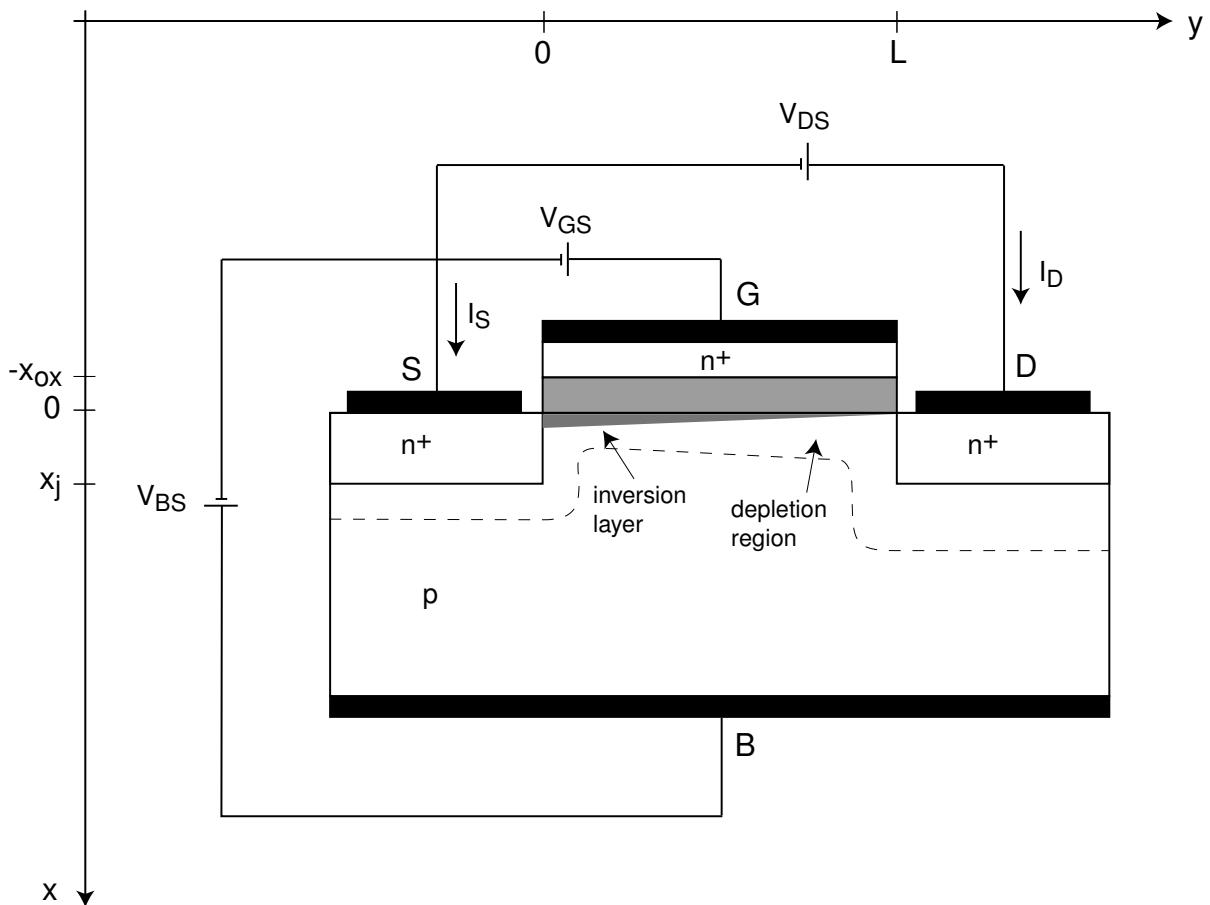


Simplifying assumptions:

- Carrier flow is one dimensional.
- Uniform doping levels
- Electron transport in inversion layer takes place by drift (*i.e.*, neglect diffusion).
- Electrons drift along the inversion layer in the mobility regime, *i.e.*, the electron velocity is proportional to the lateral electric field along the inversion layer.
- Neglect *body effect* (dependence of  $V_T$  with  $y$ )
- No parasitic resistances

- Ignore junction sidewall effects.
- No three-dimensional effects (device scales perfectly with its width).
- Neglect impact of substrate that surrounds the transistor

Definitions of spacial coordinates and voltages:



## Key conclusions

- *Deep depletion*: condition of MOS structure suddenly switched from below threshold to above threshold.
- Application of voltage to inversion layer with respect to substrate shifts threshold voltage:  $V_{SB} \uparrow \Rightarrow V_{th} \uparrow$ .